

PRODUCT NO.
73725

PRODUCT NUMBER CODE

73725-X X X X LF

HOUSING COLOR OPTION
0-WHITE
1-BLACK

SENSOR CONTACT OPTION
0-WITH SENSOR CONTACT
1-WITHOUT SENSOR CONTACT

SHIELD PLATING OPTION
1- 1.25μm MINIMUM NICKEL UNDERPLATE & 2.5μm MINIMUM BRIGHT TIN OVER ALL AREA. (HOLD DOWN STYLE "A")
2- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "B")
3- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "A")
4- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5μm MINIMUM BRIGHT TIN OVER ALL AREA. (HOLD DOWN STYLE "B")
5- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "C")
6- 1.25μm MINIMUM NICKEL ONLY. (HOLD DOWN STYLE "A")
7- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5 μm MINIMUM MATTE TIN PLATED OVER ALL. (HOLD DOWN STYLE "A")
8- 1.25μm MINIMUM NICKEL UNDERPLATED & 2.5 μm MINIMUM MATTE TIN PLATED ALL AREA. (HOLD DOWN STYLE "B")
9- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL; 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "D")
S- 1.25μm MINIMUM NICKEL ONLY.(HOLD DOWN STYLE "A"). HIGH PERFORMANCE MATERIAL FOR 12,000 DURABILITY CYCLES
A- 1.25μm MINIMUM NICKEL PLATED OVER ALL 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "F")
B- 1.25μm MINIMUM NICKEL PLATED OVER ALL 2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY (HOLD DOWN STYLE "F")

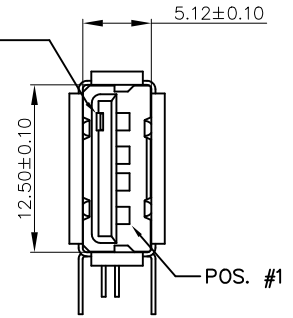
TERMINAL OPTION
50u" NI UNDERPLATE; 30u" GXT CONTACT AREA,100u" TIN TAIL AREA;
0- DIM "A": 2.29 (TERMINAL TAIL LENGTH);
1- DIM "A": 3.71 (TERMINAL TAIL LENGTH);

LEAD FREE OPTION
SEE NOTE 9

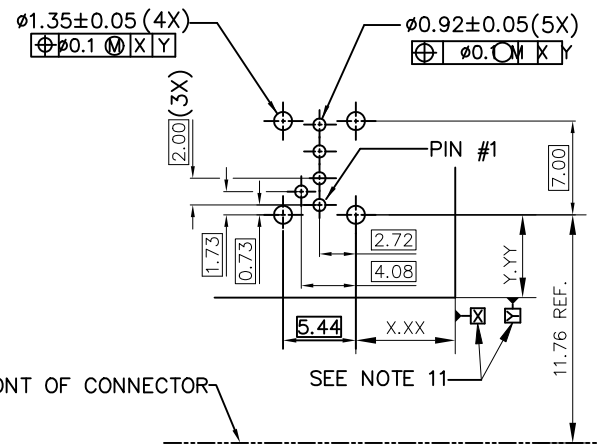
PACKAGING OPTION
B - TUBE
R - TAPE&REEL



SENSOR CONTACT

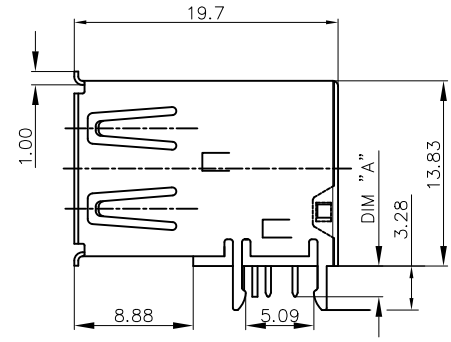


WITH SENSOR CONTACT



FRONT OF CONNECTOR

PC BOARD MOUNTING DIMENSIONS FOR 5 PIN



FOR 73725-X0X0B
HOLD DOWN STYLE "A"

NOTES:

- MATERIAL:
CONTACTS: COPPER ALLOY
SHIELD: COPPER ALLOY
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: SEE PRODUCT CODE
- PLATING:
CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76μm MINIMUM) IN CONTACT AREA; 2.5 μm TIN MINIMUM IN SOLDER TAIL AREA.
SHIELD: 1.27 μm MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
(THE PLATING MEASURE POINT ON THE SHIELD HOLD DOWN AREA ONLY).
- DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- RECOMMENDED PCB BOARD THICKNESS IS 1.00 ~ 1.60mm EXCEPT 73725-1191BLF; 73725-1191BLF CAN BE USED FOR THE PCB BOARD THICKNESS 2.30 ~ 2.65mm.
- MAXIMUM PANEL THICKNESS TO BE 2.67mm IF MOUNTED BEHIND PANEL
- METAL SHELL SLIVER 0.20 MAX.
- NI PLATING DOES NOT COMPLY WITH THE USB STANDARDS (TO BE CONTINUED)

mat'l. code				surface123/tolerance			projection		product family		
				ISO 1302	ISO 406	ISO 1101			HPL 511 USB 2.0		
ltr	ecn no	dr	date	tolerances unless otherwise specified			mm		title		
AJ	ELX-N-27708	LZ	2017/08/15	angles	linear				USB UP-RIGHT RECEPT		
AD	ELX-N-012006	A.ZH	06/25/2012	0±2°			scale 1:1				
AE	ELX-N-13463	A.ZH	11/14/2012	dr	PAMP	5/20/97			dwg no		
AF	ELX-N-14592	J.HAN	06/10/2013	engr	R Y LIU	5/20/97			sheet 1 of 4		
AG	ELX-N-21594	LQ	08/04/2015	chr	R Y LIU	5/20/97			73725		
AH	ELX-N-21919	LQ	08/04/2015	appd	JENN TSAO	5/20/97			type Product Customer Drawing		
sheet	revision										
index	sheet										

PRODUCT NO.
73725

(CONTINUED)

8. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S

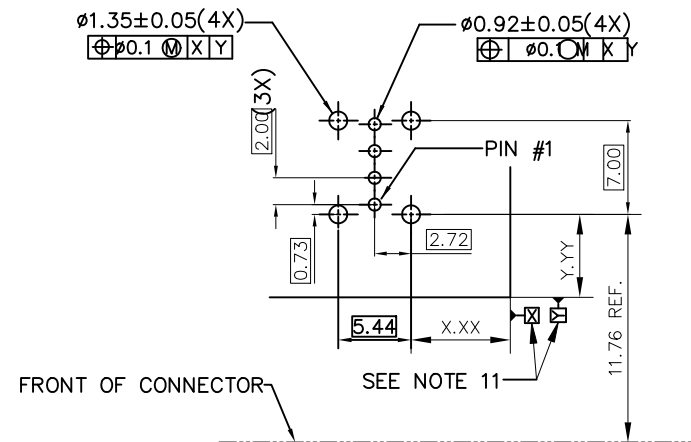
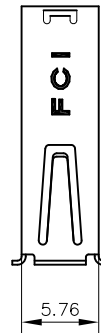
FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

FOR THE PRODUCTS WITH THE METAL SHELL PLATING NICKEL AND MATTE SN CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW PROCESS; FOR THE PRODUCTS WITH METAL SHELL PLATING BRIGHT SN OR SEMI-BRIGHT SN CAN'T WITHSTAND REFLOW AND JUST CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDERING PROCESS.

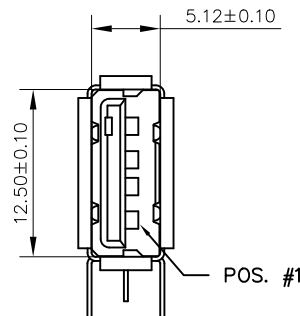
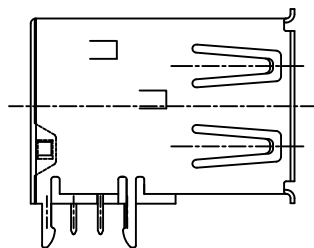
FOR ALL LEAD FREE P/N'S, WITH SUFFIX LF.

12. THE PRODUCT CAN BE USED FOR PIP PROCESS

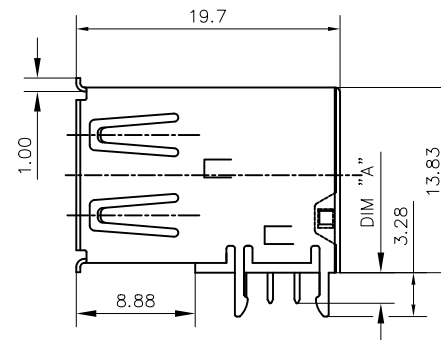
13. DATUM OF CUSTOMER'S PCB LAYOUT.



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN

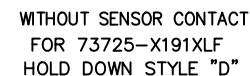
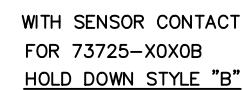
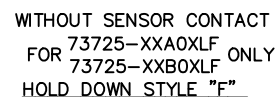
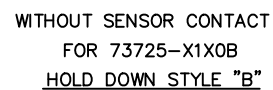


WITHOUT SENSOR CONTACT



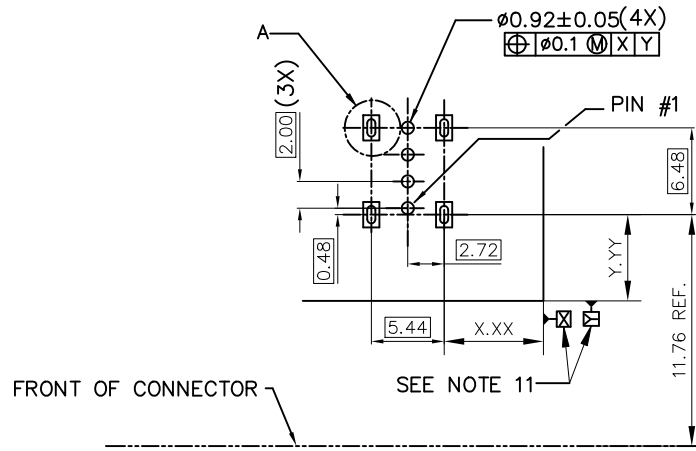
FOR 73725-X1X0B
HOLD DOWN STYLE "A"

mat'l. code				surface ¹²³ /tolerance			projection		product family		
				ISO 1302 ✓			ISO 406 ISO 1101		HPL 511 USB 2.0		
ltr ecn no dr date				tolerances unless otherwise specified			mm		title		
AJ				angles linear			mm		USB UP-RIGHT RECEPT		
				0°±2'			scale 1:1				
				dr PAMP 5/20/97					dwg no sheet2 of 4 size		
				engr R Y LIU 5/20/97					73725 A3		
				chr R Y LIU 5/20/97							
				appd JENN TSAO 5/20/97					type Product Customer Drawing		
sheet index		revision sheet									

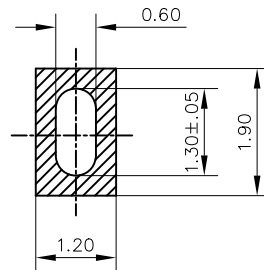


mat'l. code				surface ¹²³ /tolerance ISO 1302 ✓ ISO 406 ISO 1101		projection 		product family HPL 511 USB 2.0			
ltr	ecr no	dr	date	tolerances unless otherwise specified				title USB UP-RIGHT RECEPT			
AJ				angles linear .0±.30							
				.00±.20							
				0°±2' .000±.10		scale 1:1					
				dr	PAMP	5/20/97	Amphenol FCI		dwg no sheet 3 of 4 size		
				engr	R Y LIU	5/20/97			73725 A3		
				chr	R Y LIU	5/20/97					
				appd	JENN TSAO	5/20/97			type Product Customer Drawing		
sheet index	revision sheet										

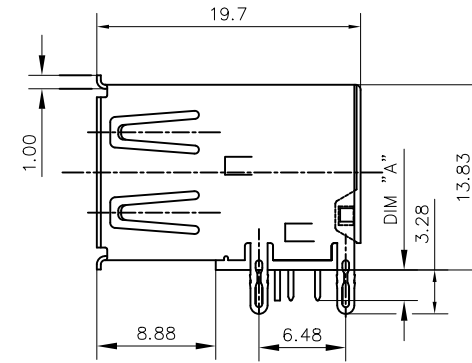
PRODUCT NO.
73725



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN



DETAIL A 5 : 1



WITHOUT SENSOR CONTACT
FOR 73725-X150B
HOLD DOWN STYLE "C"

mat'l. code					surface ¹²³ /tolerance			projection			product family						
					ISO 1302 ☒ ISO 406 ISO 1101						HPL 511 USB 2.0						
ltr		ecn no		dr	date		tolerances unless otherwise specified			title							
AJ							angles		linear	.0±.30		USB UP-RIGHT RECEPT					
										.00±.20							
							0°±2°			.000±.10							
										scale 1:1							
							dr		PAMP		5/20/97		dwg no		sheet4 of 4		size
							engr		R Y LIU		5/20/97		73725		A3		
							chr		R Y LIU		5/20/97						
							appd		JENN TSAO		5/20/97		type		Product Customer Drawing		
sheet index		revision sheet															